

NQFP 44, 7x7
CASE 560BK-01
ISSUE O

DATE 19 SEP 2008

SYMBOL	PITCH VARIATION A			PITCH VARIATION B			PITCH VARIATION C			PITCH VARIATION C		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.80	BSC		0.65	BSC		0.50	BSC		0.50	BSC	
N	28			32			44			44		
Nd	7			8			11			11		
Ne	3			3			3			3		
L	0.50	0.60	0.75	0.50	0.60	0.75	0.50	0.60	0.75	0.30	0.40	0.50
b	0.28	0.33	0.40	0.23	0.28	0.35	0.18	0.23	0.30	0.18	0.23	0.30
D2	SEE EXPOSED PAD VARIATION: *											
E2	SEE EXPOSED PAD VARIATION: *											

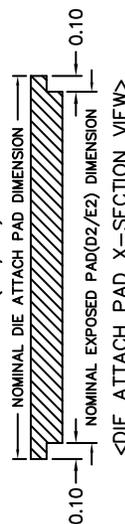
* NOT DESIGNED YET
 ** DESIGNED BUT NOT TOOLED UP

SYMBOL	PITCH VARIATION D			PITCH VARIATION E		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.50	BSC		0.40	BSC	
N	48			56		
Nd	12			14		
Ne	3			3		
L	0.30	0.40	0.50	0.30	0.40	0.50
b	0.18	0.23	0.30	0.15	0.20	0.25
D2	SEE EXPOSED PAD VARIATION: C,F,G,H					
E2	SEE EXPOSED PAD VARIATION: C,F,G,H					

<STANDARD>

SYMBOLS	D2			E2			NOTE
	MIN	NOM	MAX	MIN	NOM	MAX	
A	3.20	3.30	3.40	3.20	3.30	3.40	
B	3.70	3.80	3.90	3.70	3.80	3.90	
C	4.00	4.10	4.20	4.00	4.10	4.20	
D	4.60	4.70	4.80	4.60	4.70	4.80	
E	4.80	4.90	5.00	4.80	4.90	5.00	
F	5.00	5.10	5.20	5.00	5.10	5.20	
G	5.20	5.30	5.40	5.20	5.30	5.40	
H	5.40	5.50	5.60	5.40	5.50	5.60	

GENERAL ; NOMINAL EXPOSED PAD(D2/E2) DIMENSION = NOMINAL DIE ATTACH PAD DIMENSION-0.20



NOTE:

ABOVE GENERAL CORRELATION BETWEEN NOMINAL EXPOSED PAD DIMENSION AND NOMINAL DIE ATTACH PAD DIMENSION MAY BE APPLICABLE FOR AMKOR PACKAGE ONLY. OTHER SUBCONS MAY FOLLOW DIFFERENT CORRELATION RULE FOR PACKAGE.

SYMBOL	COMMON DIMENSIONS		
	MIN.	NOM.	MAX.
A	0.80	0.85	0.90
A1	0.00	0.01	0.05
A2	0.60	0.65	0.70
A3	0.20 REF.		
D	7.00 BSC		
D1	6.75 BSC		
E	7.00 BSC		
E1	6.75 BSC		
θ	0	-	12°
P	0.24	0.42	0.60
Q	0.30	0.40	0.65
R	0.13	0.17	0.23

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- NOTES:
1. DIE THICKNESS ALLOWABLE IS 0.305mm MAXIMUM(.012 INCHES MAXIMUM)
 2. DIMENSIONING & TOLERANCES CONFORM TO ASME Y14.5M. – 1994.
 3. N IS THE NUMBER OF TERMINALS.
Nd IS THE NUMBER OF TERMINALS IN X-DIRECTION &
Ne IS THE NUMBER OF TERMINALS IN Y-DIRECTION.
 4. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL TIP.
 5. THE PIN #1 IDENTIFIER MUST BE EXISTED ON THE TOP SURFACE OF THE PACKAGE BY USING INDENTATION MARK OR OTHER FEATURE OF PACKAGE BODY.
 6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
 7. ALL DIMENSIONS ARE IN MILLIMETERS.
 8. THE SHAPE SHOWN ON FOUR CORNERS ARE NOT ACTUAL I/O.
 9. BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
 10. APPLIED ONLY FOR TERMINALS.
 11. Q AND R APPLIES ONLY FOR STRAGHT TIEBAR SHAPES.
 12. FOR 0.40mm LEAD PITCH, THE LEAD POSITION TOLERANCE MUST BE 0.07mm AT THE ACTUAL MEAN VALUE OF BODY SIZE.
 13. REFERENCE ANAM 45277, VERSION 14

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